L Number	Hits	Search Text	DB	Time stamp
1	2	(temporary) same (back near side near5 etch$3)	USPAT, US-PGPUB	2002/11/05 14:44
2	10867	(field near oxide or "FOX") same etch$3	USPAT, US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 15:05
3	11	((field near oxide or "FOX") same etch$3) same (back near side near etch$3)	USPAT, US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 14:47
4	0	(((field near oxide or "FOX") same etch$3) same (back near side near etch$3)) same protective	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 14:48
5	11	(((field near oxide or "FOX") same etch$3) same (back near side near etch$3)) and (protect$3 near film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 14:49
6	509	((field near oxide or "FOX") same etch$3) and (protective near layer)	USPAT US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 15:06
7	145	(((field near oxide or "FOX") same etch$3) and (protective near layer)) and (back near3 etch$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 15:26
8	5	((((field near oxide or "FOX") same etch$3) and (protective near layer)) and (back near3 etch$3)) and ((fluid near eject$3) or (print near head))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 15:08
9	130	((((field near oxide or "FOX") same etch$3) and (protective near layer)) and (back near3 etch$3)) and (mask$3 or capp$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 15:35
10	82	(((((field near oxide or "FOX") same etch$3) and (protective near layer)) and (back near3 etch$3)) and (mask$3 or capp$3)) and (hole or oppen$3 or groove or (through near hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 15:56
11	4722929	open$3 or slot or hole or through near hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 16:05
12	84836	(open$3 or slot or hole or through near hole) and (ink or fluid near eject$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 16:06
13	41396	(open$3 or slot or hole or through near hole) same (ink or fluid near eject$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 16:17
14	30907	((open$3 or slot or hole or through near hole) same (ink or fluid near eject$3)) and (fill$3 same trench or open$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 16:11

15	17	(((open$3 or slot or hole or through near hole) same (ink or fluid near eject$3)) and (fill$3 same trench or open$3)) and (back near side near etch$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 16:40
16	2335	plug same (back near3 etch$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 16:41
17	3949	(plug or protect$3) same (back near3 etch$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 16:42
18	1904	((plug or protect$3) same (back near3 etch$3)) same (slot or open$3 or hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 16:43
19	1248	(((plug or protect$3) same (back near3 etch$3)) same (slot or open$3 or hole)) and @pd<20010622	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 16:44
20	59	((((plug or protect$3) same (back near3 etch$3)) same (slot or open$3 or hole)) and @pd<20010622) and (eject$3 or print$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 16:45
-	0	(hole near5 plug) same (back near side near5 etch$3)	USPAT; US-PGPUB	2002/11/05 14:39
-	938	(back near side near5 etch$3)	USPAT; US-PGPUB	2002/11/04 17:09
-	44	((back near side near5 etch$3)) and (hole same (front near surface))	USPAT; US-PGPUB	2002/11/04 17:11
-	25	(((back near side near5 etch$3)) and (hole same (front near surface))) and @pd<20010622	USPAT; US-PGPUB	2002/11/04 17:12
-	2	(("5734399") or ("0463413")).PN.	USPAT; US-PGPUB	2002/11/05 08:35
-	2	(("5734399") or ("5463413")).PN.	USPAT; US-PGPUB	2002/11/05 08:37
-	1892	plug same (back near3 etch$3)	USPAT; US-PGPUB	2002/11/05 08:38
-	2335	plug same (back near3 etch$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 09:17
-	2	(plug same (back near3 etch$3)) and ((print near head) or (fluid near ejection))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 08:40
-	832	(plug same (back near3 etch$3)) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 08:45
-	498	((plug same (back near3 etch$3)) and trench) and @pd<20010622	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 09:45

-	139	(((plug same (back near3 etch$3)) and trench) and @pd<20010622) and (remov$3 near5 plug)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 08:47
-	31	(((plug same (back near3 etch$3)) and trench) and @pd<20010622) and (eject$3 or print$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 10:00
-	150958	(hole or open$3) same plug	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 10:02
-	44	((hole or open$3) same plug) and (etch$3 near3 (back near side))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 11:29
-	33079	(slot or through near hole) same (die or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 11:32
-	22	((slot or through near hole) same (die or wafer)) same ((back near side) near3 etch$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 12:07
-	44	(plug same (back near3 etch$3)) and ((slot or through near hole) same (die or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 12:07

L Number	Hits	Search Text	DB	Time stamp
1	2	(("5734399") or ("0463413")).PN.	USPAT; US-PGPUB	2002/11/05 08:35
4	2	(("5734399") or ("5463413")).PN.	USPAT; US-PGPUB	2002/11/05 08:37
5	1892	plug same (back near3 etch$3)	USPAT; US-PGPUB	2002/11/05 08:38
6	2335	plug same (back near3 etch$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 09:17
7	2	(plug same (back near3 etch$3)) and ((print near head) or (fluid near ejection))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 08:40
8	832	(plug same (back near3 etch$3)) and trench	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 08:45
9	498	((plug same (back near3 etch$3)) and trench) and @pd<20010622	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 09:45
10	139	(((plug same (back near3 etch$3)) and trench) and @pd<20010622) and (remov$3 near5 plug)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 08:47
11	31	(((plug same (back near3 etch$3)) and trench) and @pd<20010622) and (eject$3 or print$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 10:00
12	150958	(hole or open$3) same plug	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 10:02
13	44	((hole or open$3) same plug) and (etch$3 near3 (back near side))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 11:29
14	33079	(slot or through near hole) same (die or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 11:32
15	22	((slot or through near hole) same (die or wafer)) same ((back near side) near3 etch$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 12:07
16	44	(plug same (back near3 etch$3)) and ((slot or through near hole) same (die or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/05 12:07
-	0	(hole near5 plug) same (back near side near5 etch$3)	USPAT; US-PGPUB	2002/11/05 08:33
-	938	(back near side near5 etch$3)	USPAT; US-PGPUB	2002/11/04 17:09
-	44	((back near side near5 etch$3)) and (hole same (front near surface))	USPAT; US-PGPUB	2002/11/04 17:11

25   ((((back near side near5 etch$3)) and (hole same (front near surface))) and @pd<20010622   USPAT   2002/11/04 17:12
US-PGPUB